

ABSTRACT

To provide a mold release film which is excellent in releasability and capable of suppressing contamination of a mold or a resin-encapsulation portion by the mold release film and which is capable of forming a resin-encapsulation portion excellent in
5 adhesion to an ink layer, and a process for producing a semiconductor package using the mold release film.

A mold release film to be disposed on a cavity surface of a mold in a method for producing a semiconductor package wherein a semiconductor element is disposed in the mold and encapsulated with a curable resin to form a resin-encapsulation portion,
10 characterized in that it has a first surface to be in contact with the curable resin at the time of forming the resin-encapsulation portion, and a second surface to be in contact with the cavity surface, at least the first surface is made of a fluororesin, and in a specific test method, F/AI is from 0.2 to 4, or $F/(C+F+O)$ is from 0.1 to 0.3.